

Weidmüller Interface GmbH & Co. KG Klingenbergstraße 26

D-32758 Detmold Germany

www.weidmueller.com

Product image





Similar to illustration

High-temperature-resistant pin header (SC-SMT 180LF) in 3.81-mm pitch (0.15 inch)

- Plugging direction is perpendicular to PCB (standing)
- With solder flange (LF).
- Packed either in box (BX) or on anti-static roll (tape-on-reel, RL)
- Pin length of either 1.5 mm or 3.2 mm

Weidmüller's 3.81-mm-pitch (0.15 inch) plug-in connectors are compatible with the layouts of standard connectors and offer space for labelling.

General ordering data

Version	PCB plug-in connector, male header, Solder flange, THT/THR solder connection, 3.81 mm, Number of poles: 16, 180°, Solder pin length (I): 3.2 mm, tinned, black, Box
Order No.	<u>1863480000</u>
Туре	SC-SMT 3.81/16/180LF 3.2SN BK BX
GTIN (EAN)	4032248428670
Qty.	50 pc(s).
Product data	IEC: 320 V / 17.5 A UL: 300 V / 11 A
Packaging	Box

Creation date March 25, 2021 9:58:23 PM CET



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Technical data

Depth	7.1 mm	Depth (inches)	0.28 inch
Height	12.4 mm	Height (inches)	0.488 inch
Height of lowest version	9.2 mm	Net weight	4.56 g
Width	71.25 mm	Width (inches)	2.805 inch

System specifications

Product family	OMNIMATE Signal - series	Type of connection	
	BC/SC 3.81		Board connection
Mounting onto the PCB	THT/THR solder	Pitch in mm (P)	
	connection		3.81 mm
Pitch in inches (P)	0.15 inch	Outgoing elbow	180°
Number of poles	16	Number of solder pins per pole	1
Solder pin length (I)	3.2 mm	Solder pin length tolerance	0 / -0,02 mm
Solder pin dimensions	d = 1.0 mm, Octagonal	Solder pin dimensions = d tolerance	0 / -0,04 mm
Solder eyelet hole diameter (D)	1.3 mm	Solder eyelet hole diameter tolerance (0)+ 0,1 mm
Outside diameter of solder pad	2.1 mm	Template aperture diameter	1.9 mm
L1 in mm	57.15 mm	L1 in inches	2.25 inch
Number of rows	1	Pin series quantity	1
Touch-safe protection acc. to DIN VDE		Touch-safe protection acc. to DIN VDE	
57 106	Safe from finger touch	0470	IP 20
Volume resistance	≤5 mΩ	Can be coded	Yes

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	Illa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Copper alloy
Contact surface	tinned	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	120 °C	Temperature range, installation, min.	-25 °C
Temperature range, installation, max.	120 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	17.5 A
Rated current, max. number of poles (Tu=20°C)	13.9 A	Rated current, min. number of poles (Tu=40°C)	17 A
Rated current, max. number of poles (Tu=40°C)	12.4 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 76 A

Technical data

SC-SMT 3.81/16/180LF 3.2SN BK BX



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nstitute (CSA)	^	Certificate No. (CSA)	
	(CD.		
	S.		
	0001/		200039-1121690
Rated voltage (Use group B / CSA)	300 V	Rated current (Use group B / CSA)	11 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		
Rated data acc. to UL 1059			
Institute (cURus)	c R us	Certificate No. (cURus)	E60693
Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	300 V
Rated current (Use group B / UL 1059)	11 A	Rated current (Use group D / UL 1059)	11 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		
Packing			
Packaging	Box	VPE length	80 mm
VPE width	85 mm	VPE height	100 mm
Classifications			
ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
Important note			
IPC conformity	Conformity: The products are dow	eloped, manufactured and delivered according	international recognized
in C contorning	standards and norms and comply	r with the assured properties in the data sheet r ass 2". Further claims on the products can be e	esp. fulfill decorative propertie
Notes	Rated current related to rated c	cross-section & min. No. of poles.	
	• Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.		
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	be designed in accordance witP on drawing = pitch	h the relevant application standards.	
	• P on drawing = pitch	h the relevant application standards. uct with average temperature of 50 °C and aver	age humidity 70%, 36 month
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Technical data

Downloads

Approval/Certificate/Document of	CB Certificate
Conformity	CB Testreport
	Declaration of the Manufacturer
Engineering Data	<u>STEP</u>
Product Change Notification	Standardization of M2.5 square nut -DE
	Standardization of M2.5 square nut -EN

Drawings

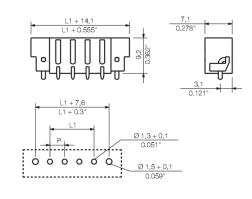


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Dimensional drawing



Wave Solder Profile

Recommended wave solderding profiles

Weidmüller 🟵

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Double Wave:

Single Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Reflow Solder Profile

Recommended reflow soldering profile



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Time [sec]

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- · Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.